

15A GLASS PASSIVATED SUPERFAST RECTIFIER

Features

- Fred Chip Planar Construction
- Superfast 35nS and 50nS Recovery Time
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- Soft Recovery Characteristics
- Epoxy Meets UL 94V-0 Classification
- Ideally Suited for Use in High Frequency SMPS, Inverters and As Free Wheeling Diodes

Mechanical Data

Case: TO-220A, Molded Plastic

Terminals: Plated Leads Solderable per

MIL-STD-202, Method 208

Polarity: See Diagram

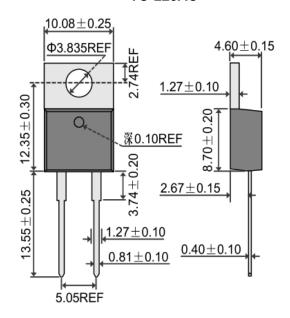
Weight: 1.9 grams (approx.)

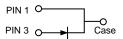
Mounting Position: Any

Mounting Torque: 0.6 N.m Max.

Lead Free: For RoHS / Lead Free Version

TO-220AC





Maximum Ratings and Electrical Characteristics @TA=25°C unless otherwise specified

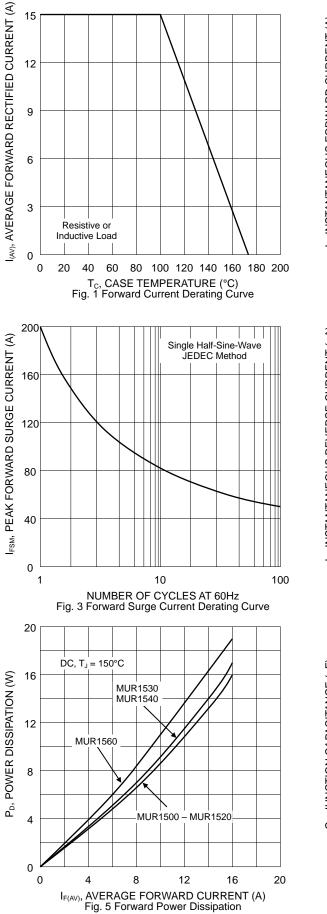
Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

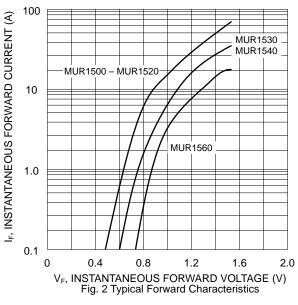
Characteristic	Symbol	MUR 1500	MUR 1510	MUR 1515	MUR 1520	MUR 1530	MUR 1540	MUR 1560	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	VRRM VRWM VR	50	100	150	200	300	400	600	V
RMS Reverse Voltage	VR(RMS)	35	70	105	140	210	280	420	V
Average Rectified Output Current @T _C = 100°C	lo	15							Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	İFSM	200							А
Forward Voltage @I _F = 15A	VFM	1.05 1.3			25	1.5	V		
	IRM	10 500						μΑ	
Reverse Recovery Time (Note 1)	trr	35 50				nS			
Typical Junction Capacitance (Note 2)	Cı	175 145					145	pF	
Thermal Resistance Junction to Ambient Thermal Resistance Junction to Case	R JA R JC	73 1.5						°C/W	
Operating and Storage Temperature Range	TJ, TSTG	-65 to +175							°C

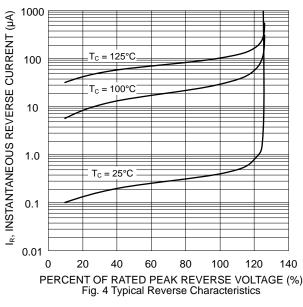
Note: 1. Measured with I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A. 2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

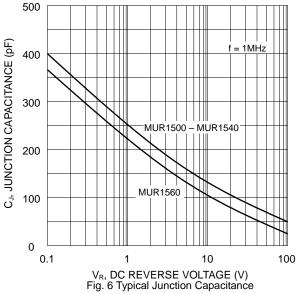






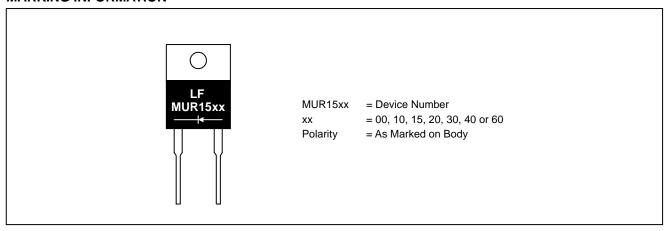








MARKING INFORMATION



PACKAGING INFORMATION

BULK

Tube Size	Quantity	Inner Box Size	Quantity	Carton Size	Quantity	Approx. Gross Weight (KG)
L x W x H (mm)	(PCS)	L x W x H (mm)	(PCS)	L x W x H (mm)	(PCS)	
525 x 31 x 6	50	558 x 150 x 40	1,000	570 x 235 x 170	5,000	11.85

RECOMMENDED SCREW MOUNTING ARRANGEMENT

Recommended isolated mounting when screw is at heatsink potential. 4-40 hardware is used.

Screw should not be tightened with any type of air-forced torque or equipment that may cause high impact on device package. The insulating bushing inside the mounting hole will insure the screw threads do not contact the metal base.

The interface should apply a layer of thermal grease or a highly conductive thermal pad for better heat dissipation.

